

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re The Application of: David Chong Sook Lim et al. Serial No.: 10/664,982  Filed: September 17, 2003  For: PACKAGING SYSTEM FOR DIE- UP CONNECTION OF A DIE-DOWN ORIENTED INTEGRATED CIRCUIT	Examiner: Leonardo Andujar  Art Unit: 2826
	Cesari and McKenna, LLP 88 Black Falcon Avenue Boston, MA 02210 September 7, 2005

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Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

## **AMENDMENT**

In response to the Office action dated 05/20/2005, please find a request for an extension of one month and the corresponding fee. Please enter the following amendments: